

Layers: 2  
Material: FR4  
Finished Thickness: 1.57mm +/- 10%  
Outer Layer Copper Thickness: 1oz  
Finish: ENIG (Au:2-5u")  
Soldermask (Color): Both Sides, LPI (Black)  
Silkscreen (Color): Both Sides, White

### **Electrical test**

FINISH: THIS BOARD SHALL BE IMMERSION GOLD PLATED ACCORDING TO IPC-6012.  
THICKNESS SHALL BE .050uM OVER 3-6uM NICKEL.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED, EXCEPT VIAS .500 FINISH OR SMALLER.

### **Layer Key:**

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\*.GM4: Board Outline

\*.TXT: NC Drill File

\*.GTP: Top Paste

\*.GTO: Top Silkscreen

\*.GTS: Top Soldermask

\*.GTL: Top Copper Layer

\*.GBL: Bottom Copper Layer

\*.GBS: Bottom Soldermask

\*.GBO: Bottom Silkscreen

\*.GBP: Bottom Paste





